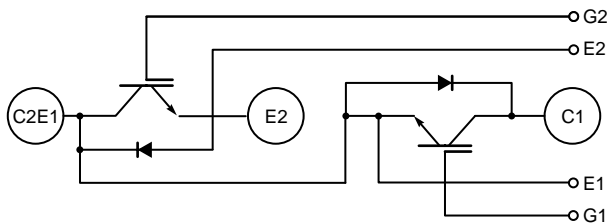
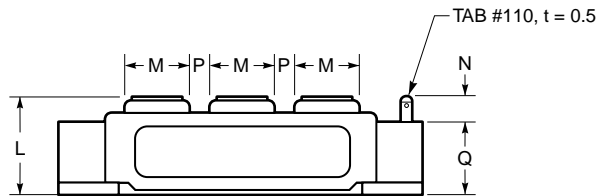
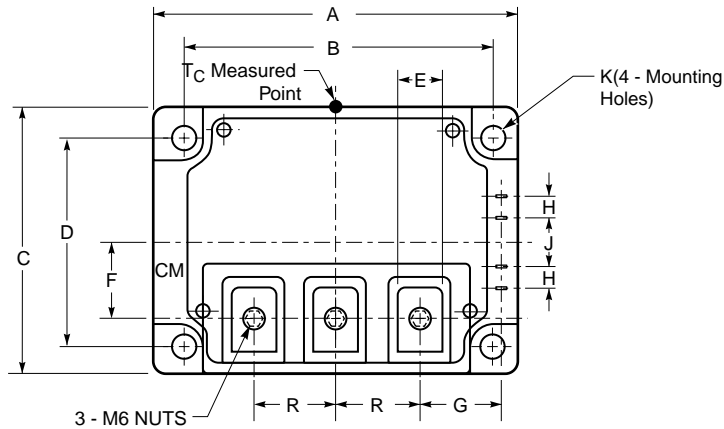


MITSUBISHI IGBT MODULES  
**CM350DU-5F**  
 HIGH POWER SWITCHING USE  
 INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.66±0.01	93.0±0.25
C	3.15	80.0
D	2.44±0.01	62.0±0.25
E	0.55	14.0
F	0.86	21.75
G	0.94	24.0
H	0.24	6.0

Dimensions	Inches	Millimeters
J	0.59	15.0
K	0.26 Dia.	6.5 Dia.
L	1.14 +0.04/-0.02	29 +1.0/-0.5
M	0.71	18.0
N	0.33	8.5
P	0.28	7.0
Q	0.83	21.0
R	0.98	25.0



**Description:**

Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of two IGBTs in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

**Features:**

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- High Frequency Operation
- Isolated Baseplate for Easy Heat Sinking

**Applications:**

- UPS
- Forklift

**Ordering Information:**

Example: Select the complete module number you desire from the table - i.e. CM350DU-5F is a 250V ( $V_{CES}$ ), 350 Ampere Trench Gate Design Dual IGBT Module.

Type	Current Rating Amperes	$V_{CES}$ Volts (x 50)
CM	350	5

## CM350DU-5F

HIGH POWER SWITCHING USE  
INSULATED TYPEAbsolute Maximum Ratings,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

	Symbol	Ratings	Units
Junction Temperature	$T_j$	-40 to 150	$^\circ\text{C}$
Storage Temperature	$T_{\text{stg}}$	-40 to 125	$^\circ\text{C}$
Collector-Emitter Voltage (G-E SHORT)	$V_{\text{CES}}$	250	Volts
Gate-Emitter Voltage (C-E SHORT)	$V_{\text{GES}}$	$\pm 20$	Volts
Collector Current ( $T_c = 25\text{ }^\circ\text{C}$ )	$I_c$	350	Amperes
Peak Collector Current	$I_{\text{CM}}$	700	Amperes
Emitter Current** ( $T_c = 25\text{ }^\circ\text{C}$ )	$I_E$	350	Amperes
Peak Emitter Current**	$I_{\text{EM}}$	700*	Amperes
Maximum Collector Dissipation ( $T_c = 25\text{ }^\circ\text{C}$ , $T_j \leq 150\text{ }^\circ\text{C}$ )	$P_c$	960	Watts
Mounting Torque, M6 Main Terminal	–	1.96 ~ 2.94	N · m
Mounting Torque, M6 Mounting	–	1.96 ~ 2.94	N · m
Weight	–	520	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	$V_{\text{iso}}$	2500	Vrms

\* Pulse width and repetition rate should be such that the device junction temperature ( $T_j$ ) does not exceed  $T_{j(\text{max})}$  rating.

\*\*Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	$I_{\text{CES}}$	$V_{\text{CE}} = V_{\text{CES}}$ , $V_{\text{GE}} = 0\text{V}$	–	–	1	mA
Gate Leakage Current	$I_{\text{GES}}$	$V_{\text{GE}} = V_{\text{CES}}$ , $V_{\text{CE}} = 0\text{V}$	–	–	0.5	$\mu\text{A}$
Gate-Emitter Threshold Voltage	$V_{\text{GE(th)}}$	$I_c = 35\text{mA}$ , $V_{\text{CE}} = 10\text{V}$	3.0	4.0	5.0	Volts
Collector-Emitter Saturation Voltage	$V_{\text{CE(sat)}}$	$I_c = 350\text{A}$ , $V_{\text{GE}} = 10\text{V}$ , $T_j = 25\text{ }^\circ\text{C}$	–	1.2	1.7	Volts
		$I_c = 350\text{A}$ , $V_{\text{GE}} = 10\text{V}$ , $T_j = 125\text{ }^\circ\text{C}$	–	1.10	–	Volts
Total Gate Charge	$Q_G$	$V_{\text{CC}} = 100\text{V}$ , $I_c = 350\text{A}$ , $V_{\text{GE}} = 10\text{V}$	–	1320	–	nC
Emitter-Collector Voltage*	$V_{\text{EC}}$	$I_E = 350\text{A}$ , $V_{\text{GE}} = 0\text{V}$	–	–	2.0	Volts

\* Pulse width and repetition rate should be such that the device junction temperature ( $T_j$ ) does not exceed  $T_{j(\text{max})}$  rating.Dynamic Electrical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units	
Input Capacitance	$C_{\text{ies}}$		–	–	99	nF	
Output Capacitance	$C_{\text{oes}}$	$V_{\text{CE}} = 10\text{V}$ , $V_{\text{GE}} = 0\text{V}$	–	–	4.5	nF	
Reverse Transfer Capacitance	$C_{\text{res}}$		–	–	3.4	nF	
Resistive	Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{CC}} = 100\text{V}$ , $I_c = 350\text{A}$ ,	–	–	1100	ns
	Load	Rise Time	$t_r$	$V_{\text{GE1}} = V_{\text{GE2}} = 10\text{V}$ ,	–	–	2400
Switching	Turn-off Delay Time	$t_{\text{d(off)}}$	$R_G = 7.1\Omega$ , Resistive	–	–	900	ns
	Times	Fall Time	$t_f$	Load Switching Operation	–	–	500
Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_E = 350\text{A}$ , $di_E/dt = -700\text{A}/\mu\text{s}$	–	–	300	ns	
Diode Reverse Recovery Charge	$Q_{\text{rr}}$	$I_E = 350\text{A}$ , $di_E/dt = -700\text{A}/\mu\text{s}$	–	5.7	–	$\mu\text{C}$	

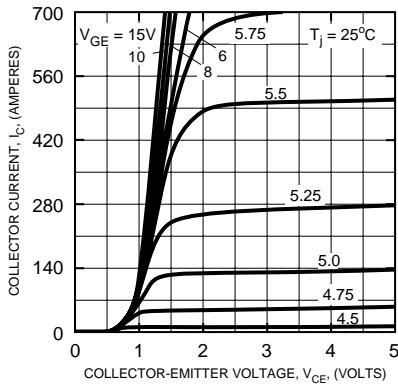
Thermal and Mechanical Characteristics,  $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{\text{th(j-c)}}$	Per IGBT	–	–	0.17	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction to Case	$R_{\text{th(j-c)}}$	Per Free-Wheel Diode	–	–	0.28	$^\circ\text{C}/\text{W}$
Contact Thermal Resistance	$R_{\text{th(c-f)}}$	Per Module, Thermal Grease Applied	–	0.010	–	$^\circ\text{C}/\text{W}$

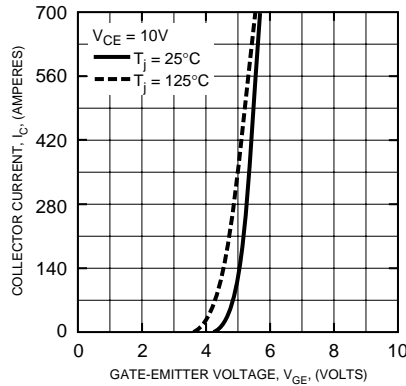
# CM350DU-5F

HIGH POWER SWITCHING USE  
INSULATED TYPE

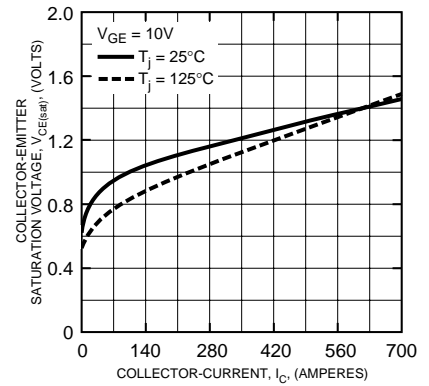
OUTPUT CHARACTERISTICS  
(TYPICAL)



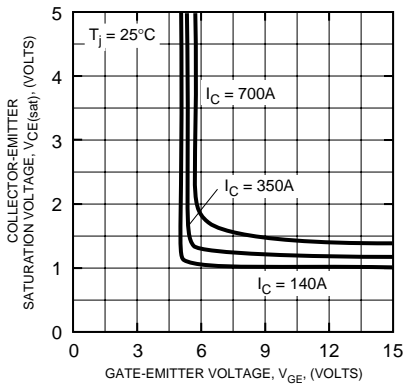
TRANSFER CHARACTERISTICS  
(TYPICAL)



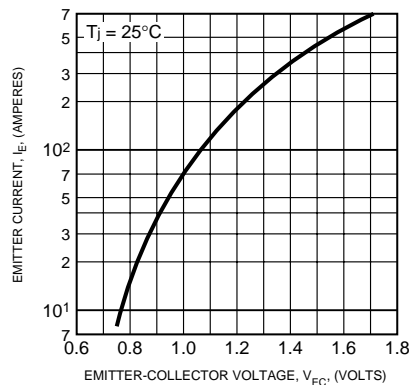
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS  
(TYPICAL)



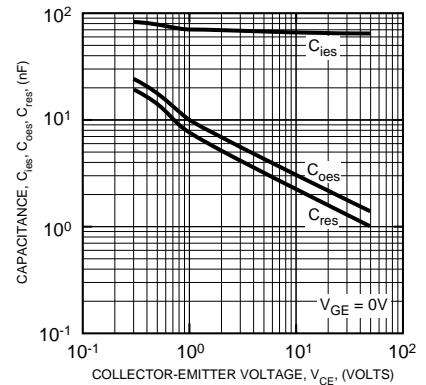
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS  
(TYPICAL)



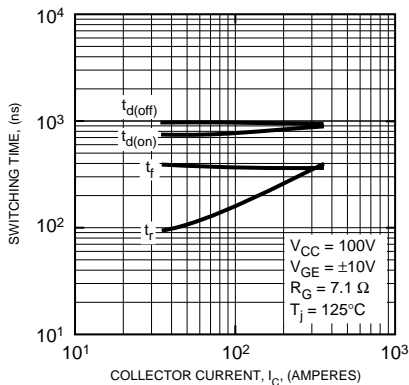
FREE-WHEEL DIODE FORWARD CHARACTERISTICS  
(TYPICAL)



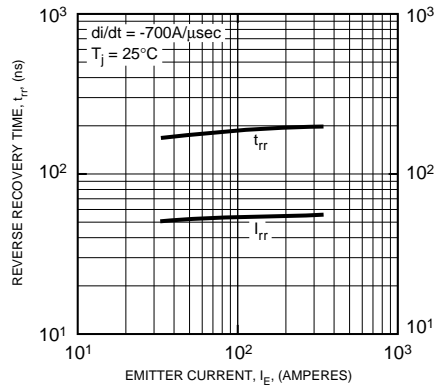
CAPACITANCE VS.  $V_{CE}$   
(TYPICAL)



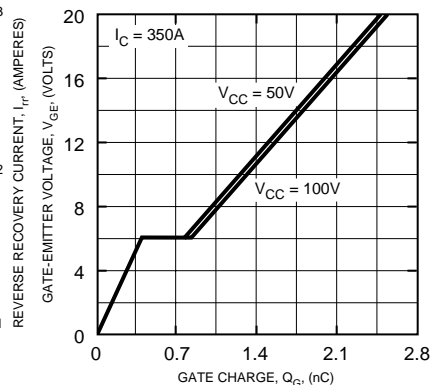
HALF-BRIDGE SWITCHING CHARACTERISTICS  
(TYPICAL)



REVERSE RECOVERY CHARACTERISTICS  
(TYPICAL)



GATE CHARGE,  $V_{GE}$



# CM350DU-5F

HIGH POWER SWITCHING USE  
INSULATED TYPE

